

PART INFORMATION

Mfg Item Number	MC35XS3400CHFKR2
Mfg Item Name	PWR QFN 24 12*12*2.1P0.9

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-11-06
Response Document ID	6187K11030D046A1.21
Contact Name	Freescale Semiconductor Inc
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DECLARATION

EU RoHS	Yes
Pb Free	No
HalogenFree	Yes
Plating Indicator	e4
EU RoHS Exemption(s)	7a

MANUFACTURING

Mfg Item Number	MC35XS3400CHFKR2
Mfg Item Name	PWR QFN 24 12*12*2.1P0.9
Version	ALL
Weight	0.928100
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	245 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7a:Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0008						g				
Epoxy Die Attach		Solvents, additives, and other materials	Proprietary Material-Other acrylates	-		0.0000706	g	88252	8.8252	76	0.0076
Epoxy Die Attach		Solvents, additives, and other materials	1,1'-(methylenedi-p-phenylene)bismaleimide	13876-54-5		0.00002648	g	33094	3.3094	28	0.0028
Epoxy Die Attach		Metals	Palladium, metal	7440-05-3		0.00000132	g	1655	0.1655	1	0.0001
Epoxy Die Attach		Plastics/polymers	Proprietary Material-Other polymers	-		0.00001324	g	16547	1.6547	14	0.0014
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.00066188	g	827358	82.7358	713	0.0713
Epoxy Die Attach		Plastics/polymers	Proprietary Material-Other Methacrylate compounds	-		0.00002648	g	33094	3.3094	28	0.0028
Solder Die Attach	0.027				7a		g				
Solder Die Attach		Lead/Lead Compounds	Lead	7439-92-1		0.024975	g	925000	92.5	26909	2.6909
Solder Die Attach		Metals	Silver, metal	7440-22-4		0.000675	g	25000	2.5	727	0.0727
Solder Die Attach		Metals	Tin, metal	7440-31-5		0.00135	g	50000	5	1454	0.1454
Die Encapsulant	0.4186						g				
Die Encapsulant		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00417554	g	9975	0.9975	4499	0.4499
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.03131672	g	74813	7.4813	33742	3.3742
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00125287	g	2993	0.2993	1349	0.1349
Die Encapsulant		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.00396665	g	9476	0.9476	4273	0.4273
Die Encapsulant		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.02296565	g	54863	5.4863	24744	2.4744
Die Encapsulant		Glass	Silica, vitreous	80676-86-0		0.35492257	g	847880	84.788	382418	38.2418
Bonding Wire, Aluminum	0.007						g				
Bonding Wire, Aluminum		Metals	Aluminum, metal	7429-90-5		0.007	g	1000000	100	7542	0.7542
Copper Lead Frame	0.45						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.4374963	g	972214	97.2214	471402	47.1402
Copper Lead Frame		Metals	Gold, metal	7440-57-3		0.00004005	g	89	0.0089	43	0.0043
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1		0.00000675	g	15	0.0015	7	0.0007
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.00736245	g	16361	1.6361	7932	0.7932
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.0017865	g	397	0.0397	192	0.0192
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.00446895	g	9931	0.9931	4815	0.4815
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.0044685	g	993	0.0993	481	0.0481
Bonding Wire	0.0067						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0067	g	1000000	100	7219	0.7219
Silicon Semiconductor Die	0.009						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00018	g	20000	2	193	0.0193
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.00882	g	980000	98	9503	0.9503
Silicon Semiconductor Die	0.009						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00018	g	20000	2	193	0.0193
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.00882	g	980000	98	9503	0.9503

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MC35XS3400CHFKR2_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MC35XS3400CHFKR2_IPC1752A.xml